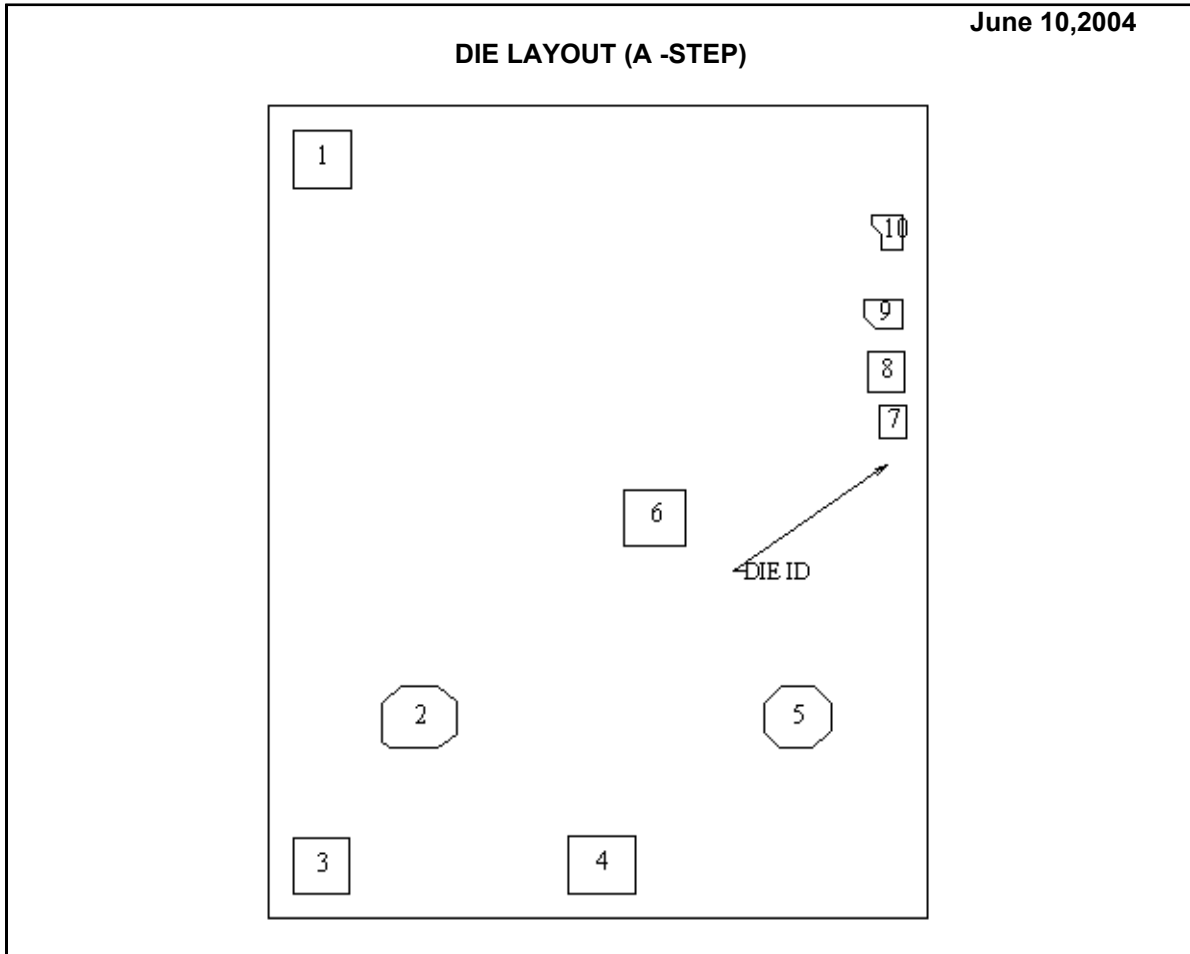


LM137H MD8 MW8
3-TERMINAL ADJUSTABLE NEGATIVE REGULATOR



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	137A	Bond Pad Opening Size (min)	188 μ m x 185 μ m
Die Step	A	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	Gold
Die Size (Drawn)	2184 μ m x 2692 μ m 86.0mils x 106.0mils	Back Side Connection	Input
Thickness	254 μ m Nominal		
Min Pitch	150 μ m Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (A -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	XY COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
Adj	1	-914	1168	193	x	193
Input	2	-591	-679	246	x	206
Output	3	-917	-1172	188	x	185
Output	4	13	-1168	218	x	193
Input	5	660	-679	224	x	206
Output	6	188	-17	208	x	185
NC	7	978	298	91	x	104
NC	8	953	462	117	x	132
NC	9	947	654	127	x	99
NC	10	959	926	104	x	114

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